

Your Complete Solutions Provider

W74M Authentication Flash

The simplest and quickest way to add "multi-layer authentication" into your existing designs

General Description

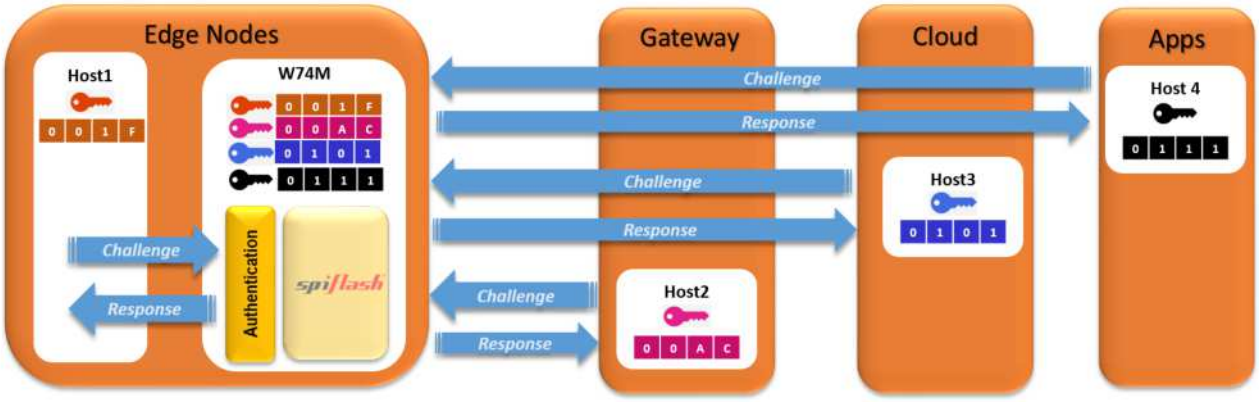
Winbond W74M product family comes with standard HMAC-SHA-256 crypto accelerator and 4 separate Monotonic Flash Counters that are HMAC-signed by individual secret keys. System utilizing each Monotonic Flash Counter can not only verify the integrity and authenticity of the counter values, but also add a timestamp to the message/information transmitted with the resistance to reply attacks. W74M enables system designers to strengthen code/data storage as well as delivers increased security for the emerging IoT demanding multi-layered authenticity.

Applications

- Emerging IoT demanding multi-layered authenticity
- Mobile accessories
- Home automation
- Industrial control
- Smart home

Use Cases

- PCBA anti-copy
- Anti-cloning to module and the whole design
- IP/Software Protection
- Root of trust



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Package Information

Voltage	Flash Density	Part number	Package
3V	1Gb	W74M01GV	WSON 8X6-mm
	512Mb	W74M51JV	WSON 8X6-mm
	256Mb	W74M25JV	WSON 8X6-mm
	128Mb	W74M12JV	WSON 6X5-mm
	64Mb	W74M64JV	SOIC8 208-mil
	0Mb	W74M00AV	SOIC8 150-mil
1.8V	1Gb	W74M01GW	WSON 8X6-mm
	512Mb	W74M51NW	WSON 8X6-mm
	256Mb	W74M25JW	WSON 8X6-mm
	128Mb	W74M12JW	WSON 8X6-mm
	64Mb	W74M64JW	WSON 6X5-mm
	0Mb	W74M00AW	SOIC8 150-mil

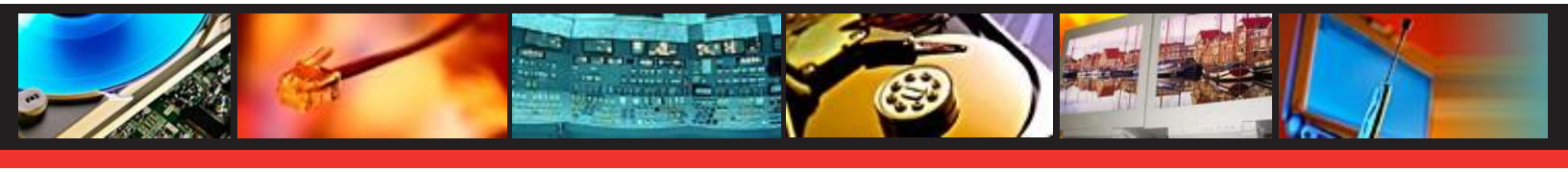
* See data sheet for further technical information. This is subject to change without notice.

Own Logic and Memory Technology

Winbond Electronics Corp. is an Integrated IC Company engaged in IC design, manufacturing and sales services. From product design, research and development, wafer fabrication to marketing of brand name product, Winbond endeavors to provide its global clientele top quality of low to medium density memory solutions.

Own 12-inch Fab

Winbond specializes in the design of high-performance, low-power memory, and riding on the strength of having a 12-inch fab, offers a whole series of SLC code storage NAND flash memory and Mobile DRAM. The in house wafer fabrication provides customers with full commitment in capacity support as well as delivery flexibility.



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